



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-01-20
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8CP1*USB4C6A	A	ZS1A	2015-01-20
Amount	UoM	Unit type	ST ECOPACK Grade	
3.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOT	1.46 - 1 - 0.57	6	flat	
Comment	Package: SOT 666; MDF valid for ESDAULC6-3BP6			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8CP1*USB4C6A					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other Inorganic Material	0.42	mg	supplier	die	Silicon (Si)	7440-21-3		0.409	mg	973810	136333
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	14286	2000
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	4762	667
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.003	mg	7143	1000
Leadframe	Copper and its alloy	0.878	mg	supplier	alloy	Copper (Cu)	7440-50-8		0.844	mg	961276	281333
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.02	mg	22779	6667
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.001	mg	1139	333
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.001	mg	1139	333
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.01	mg	11390	3333
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	1139	333
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	1139	333
Die attach	Other Organic Material	0.034	mg	supplier	glue or tape	Aluminium oxide	1344-28-1		0.008	mg	235294	2667
Die attach				supplier	glue or tape	Ethoxyethoxy-ethyl Acetate	112-15-2		0.011	mg	323529	3667
Die attach				supplier	glue or tape	Bisphenol A diglycidyl ether polymer	25036-25-3		0.005	mg	147059	1667
Die attach				supplier	glue or tape	Epoxy resin	25068-38-6		0.005	mg	147059	1667
Die attach				supplier	glue or tape	Aromatic amine	Proprietary		0.001	mg	29412	333
Die attach				supplier	glue or tape	curing & hardener	Proprietary		0.004	mg	117647	1333
Bonding Wire	Precious metals	0.045	mg	supplier	Bonding Wire	Gold (Au)	7440-57-5		0.045	mg	1000000	15000
encapsulation	Other inorganic materials	1.623	mg	supplier	Molding Compound	Silica Fused	60676-86-0		1.331	mg	820086	443667
encapsulation				supplier	Molding Compound	Epoxy Resin	Proprietary		0.123	mg	75786	41000
encapsulation				supplier	Molding Compound	Phenol Resin	Proprietary		0.082	mg	50524	27333
encapsulation				supplier	Molding Compound	Metal Hydroxide	Proprietary		0.082	mg	50524	27333
encapsulation				supplier	Molding Compound	Carbon Black	1333-86-4		0.005	mg		